



TI LM2904P Solderability Test Report

Product Model : LM2904P

Vendor :  **TEXAS INSTRUMENTS**

Package : DIP-8

Date Code : 1944+

Description : Dual General-Purpose Op Amp DIP-8

Product QTY : 10 Pcs

Sample QTY : 10 Pcs

Receive Date : 2020-10-16

Test Date : 2020-10-20

Inspection Item and Flow:

- 1 Appearance Inspection
- 2 Solderability Test
- 3 Test Result

Inspection Level:

Level II

Test Engineer	Date	Test Manager	Date
Andy Deng	2020/10/20	Joy Li	2020/10/20



一、外观检验 (Appearance Inspection)

The appearance shall be free from deformation,oxidation,contamination,crack and mark as required.

二、可焊性测试 (Solderability Test)

2.1 测试环境 Test Environment

Test Equipment : SiWeiGuan HDVS200 Digital Camera

JF-101A Microcomputer lead-free solder pot

Flux: KYX-803 (5L) Made in China

Solder Tin: Ausbond SN99.3CU0.7

Ambient Temperature : 25.5/46.5% RH

Test Method : 1. Check the sample and capture the photos for the top and bottom of the pads(Pin);

2. Power ON the solder pot and preheat for 30 minutes until the temperature is stable at 245 de grees;

3. Soak the pad/Pin at one end of the product in flux for 2 to 3 seconds, and then immerse the pad/Pin in the tin furnace;

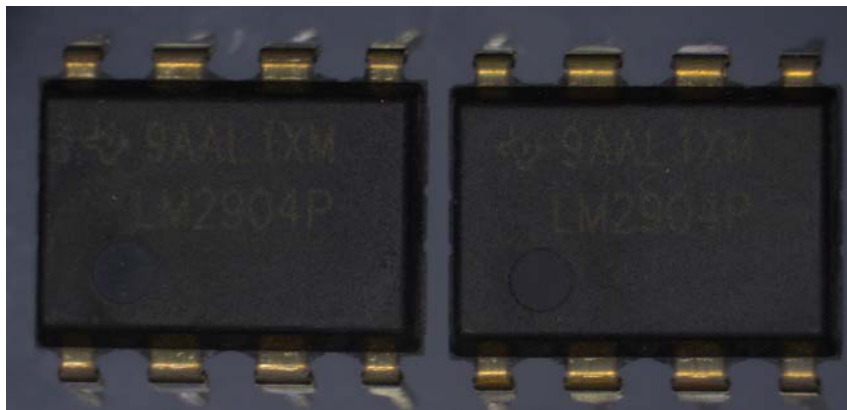
4. Repeat step 3 and test another samples;

5. After testing all the samples, confirm the tin eating degree of pads and capture the photos;

Pass conditions : Well tinned(>=95% covered) and No visible damage

2.2 Test Capture:

Product Picture



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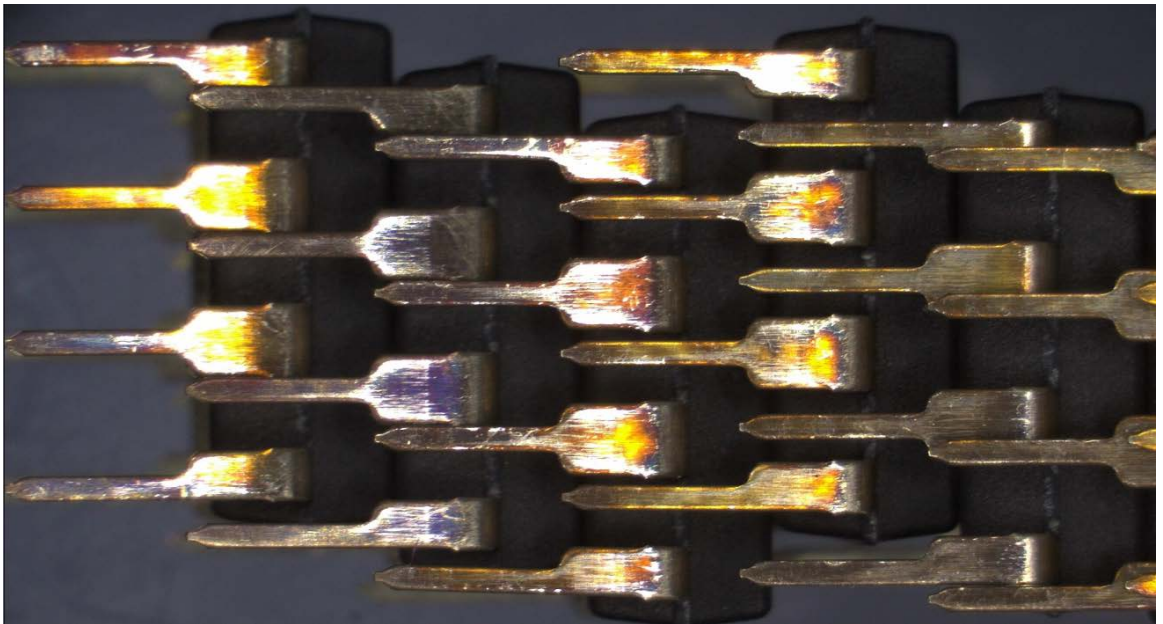
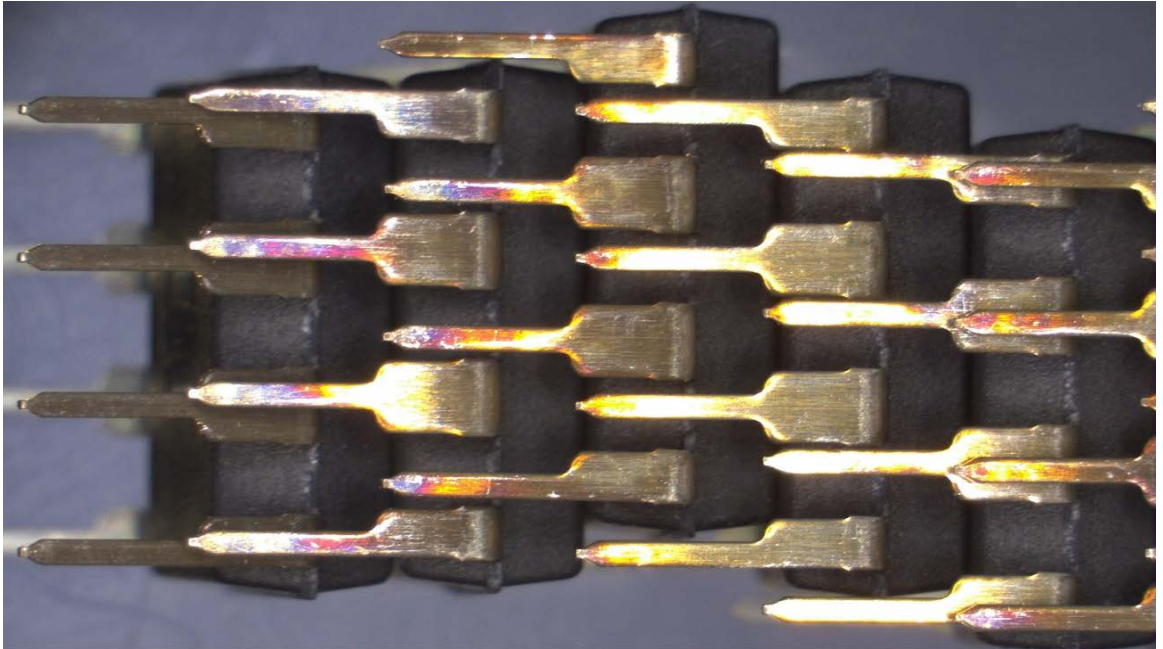
Solder pot



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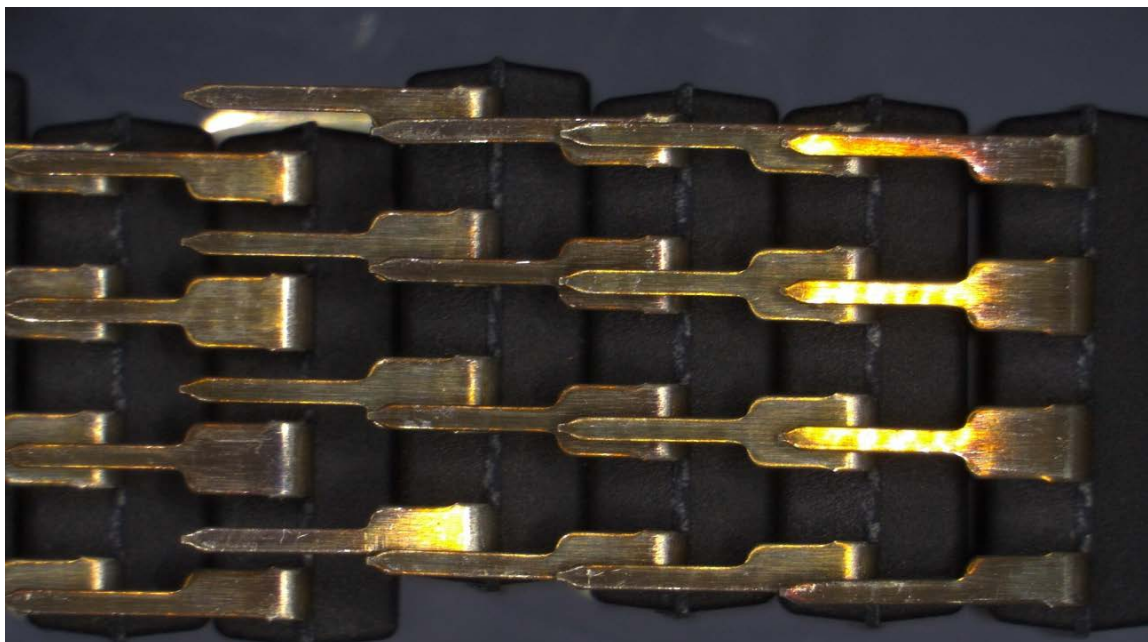
Before Test(One Side)

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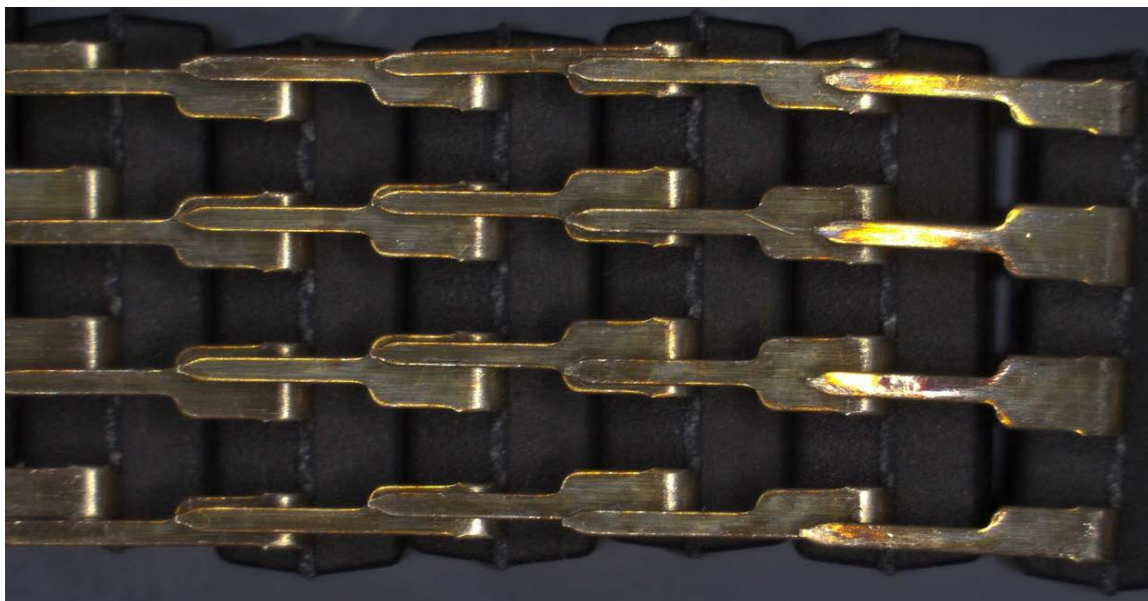


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Before Test(Another Side)



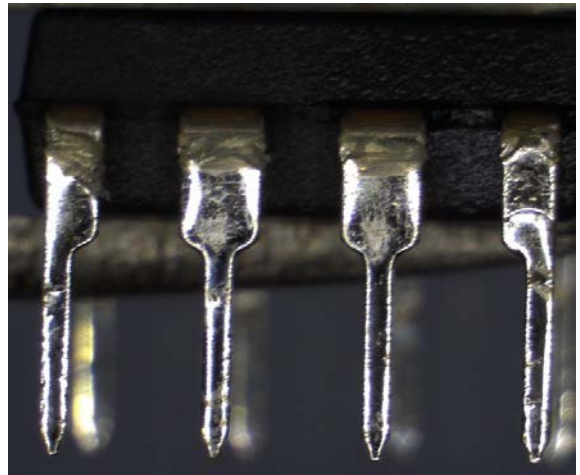
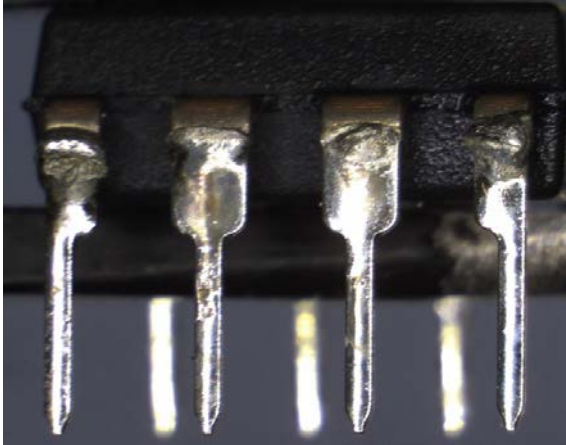
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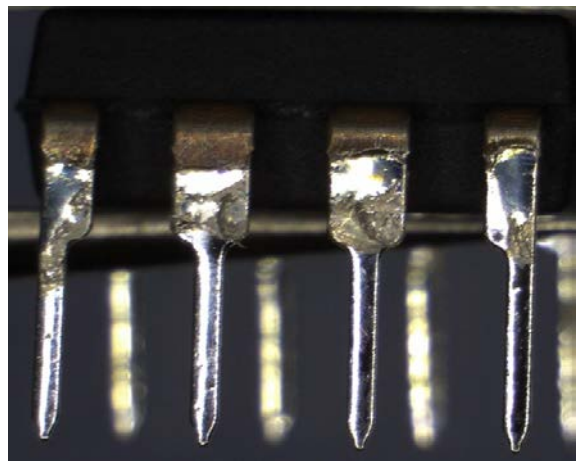
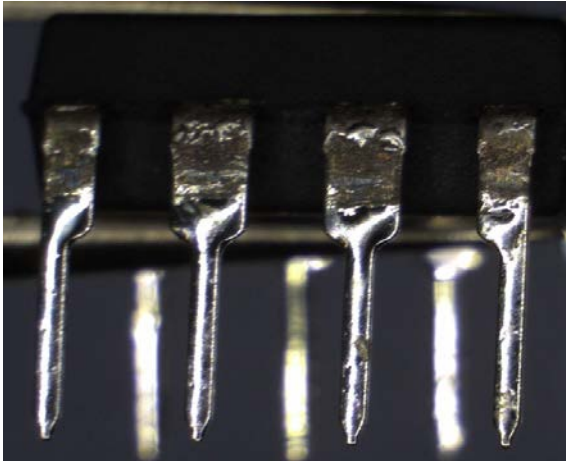
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After Test

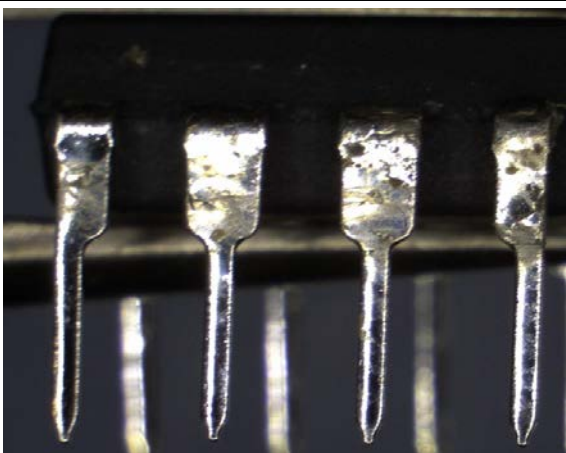
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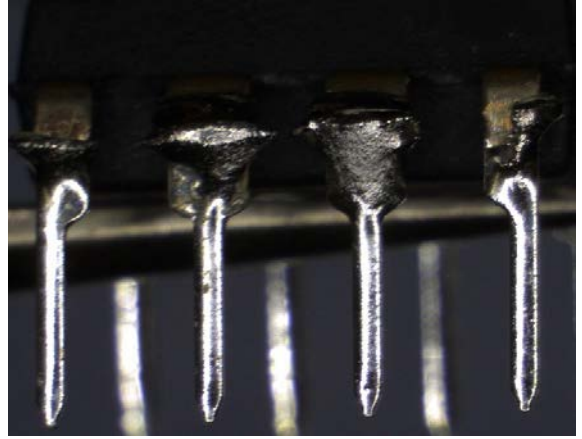
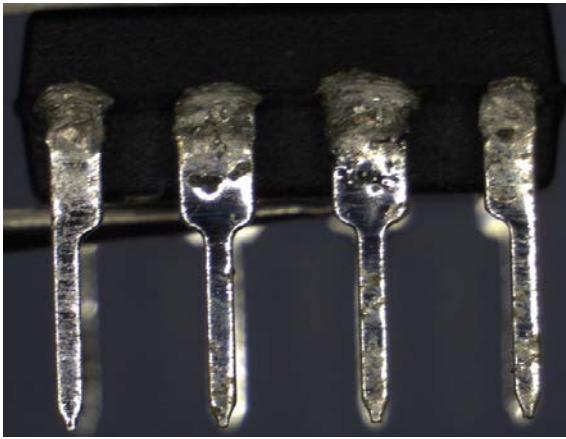


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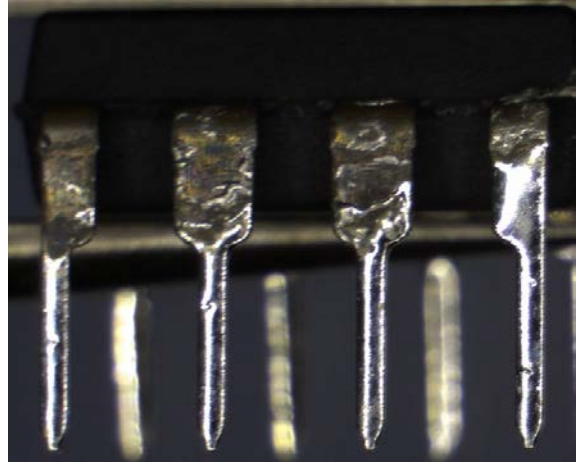
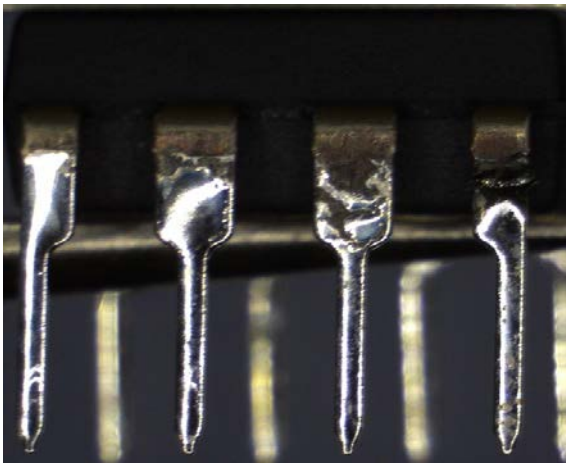


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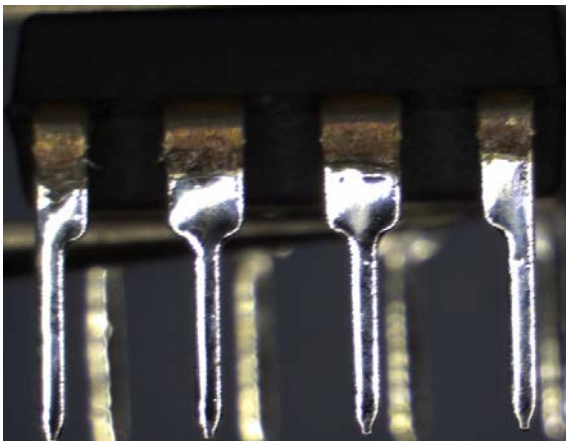
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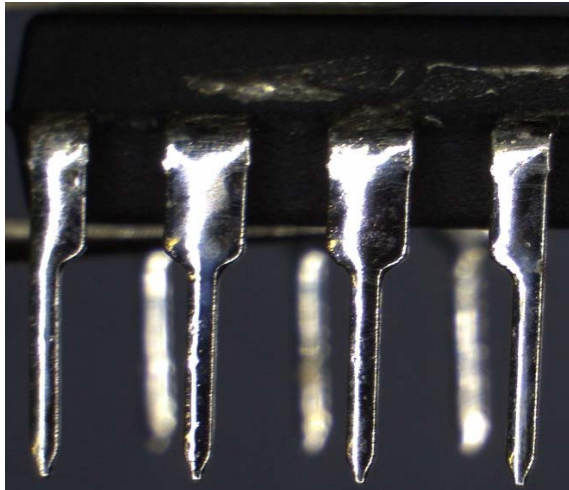
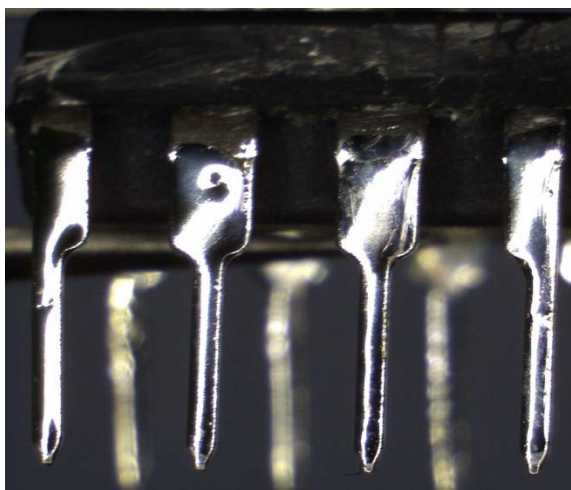


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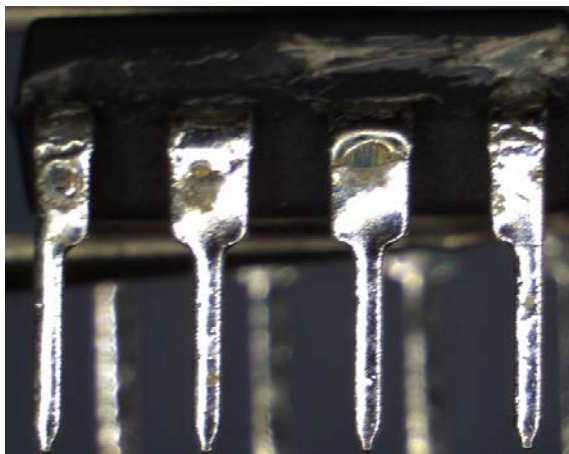
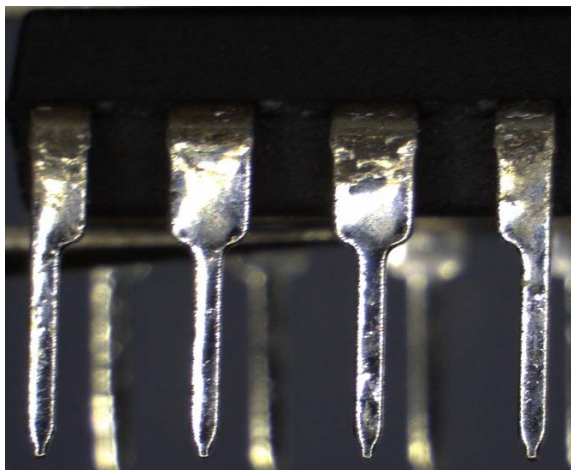


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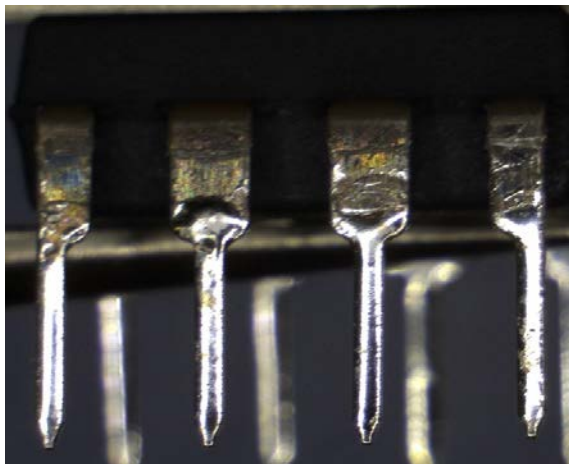
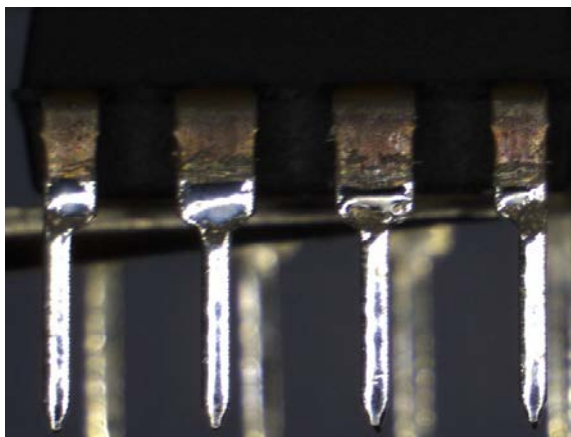
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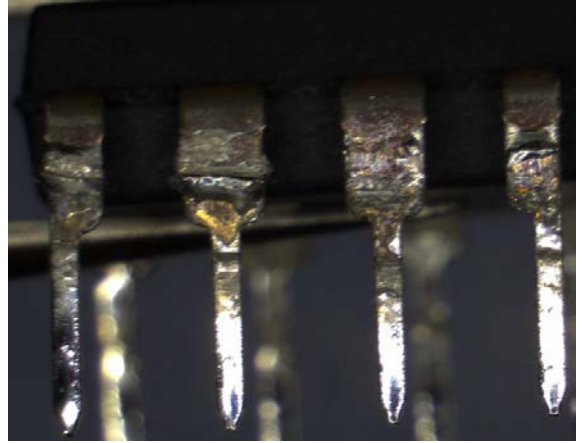
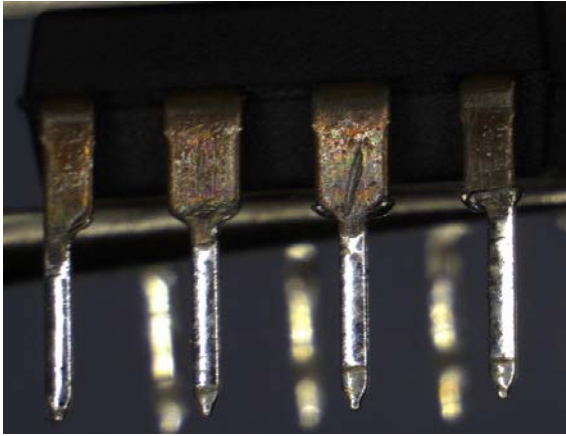


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三、测试结果 (Test Result) :

After confirmation, Some of the Sample solderability were not greater than 95%.

Test Result **NG**.

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